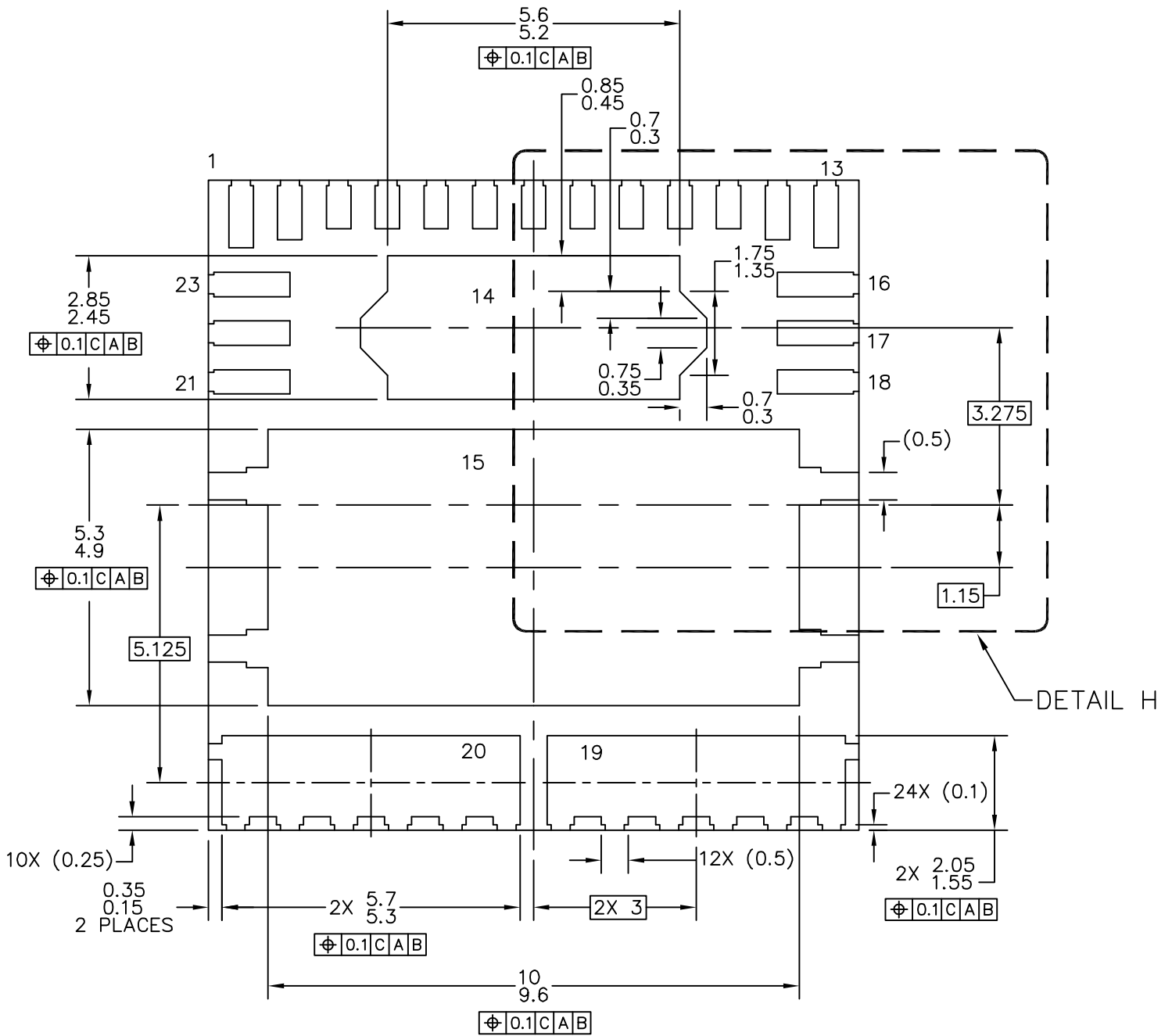
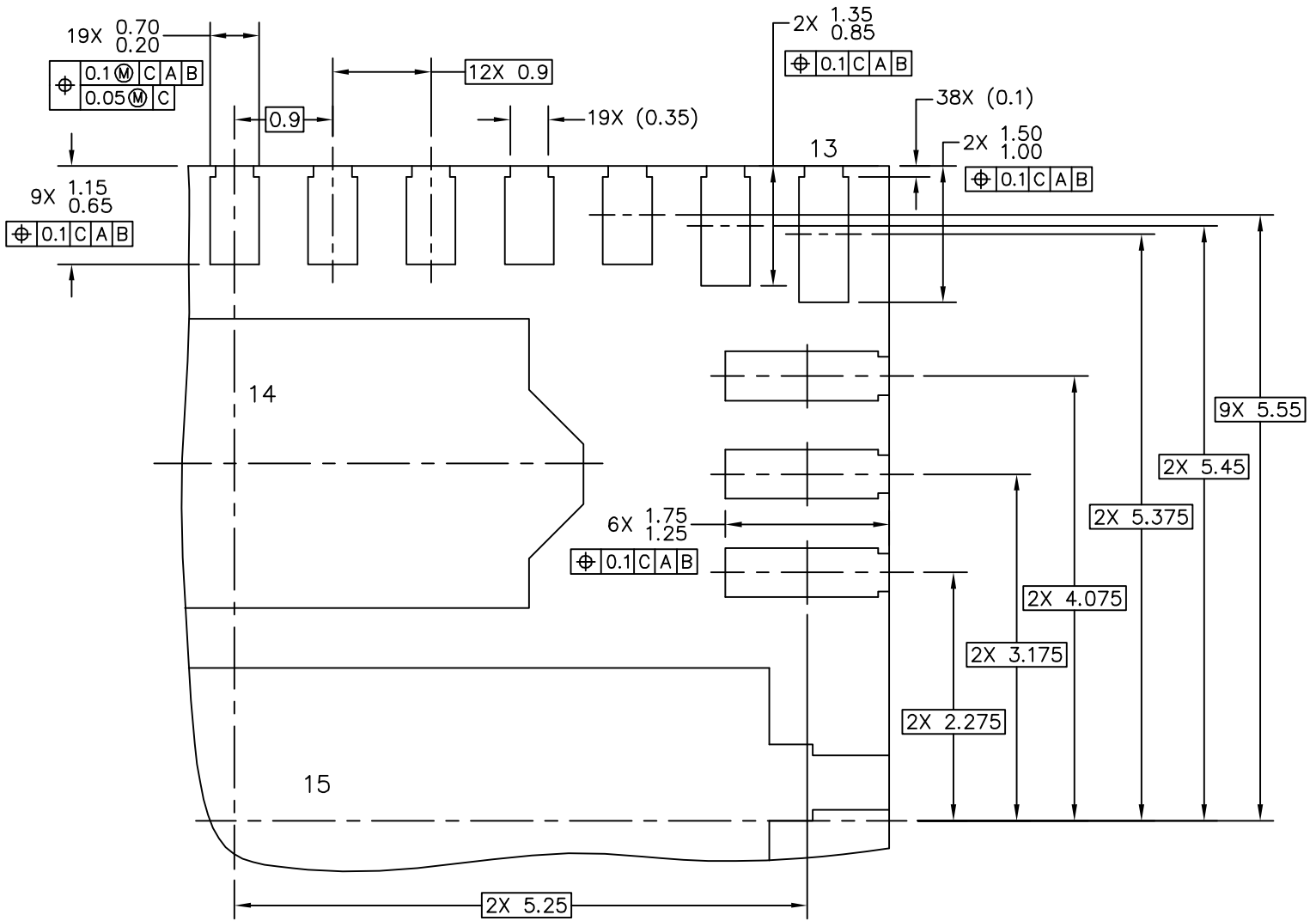


© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: PQFN-EP, 12 X 12 X 2.1 PKG, 0.90 MM PITCH, 23 I/O	DOCUMENT NO: 98ASA00495D	REV: A
	STANDARD: NON-JEDEC	
	SOT1631-5	11 JAN 2016



VIEW M-M

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: PQFN-EP, 12 X 12 X 2.1 PKG, 0.90 MM PITCH, 23 I/O	DOCUMENT NO: 98ASA00495D	REV: A
	STANDARD: NON-JEDEC	
	SOT1631-5	11 JAN 2016




DETAIL H

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: PQFN-EP, 12 X 12 X 2.1 PKG, 0.90 MM PITCH, 23 I/O	DOCUMENT NO: 98ASA00495D	REV: A
	STANDARD: NON-JEDEC	
	SOT1631-5	11 JAN 2016



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PQFP-N.
4.  COPLANARITY APPLIES TO LEADS AND CORNER LEADS.
5. MINIMUM METAL GAP IS GUARANTEED TO BE 0.25MM.

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE	
TITLE: PQFN-EP, 12 X 12 X 2.1 PKG, 0.90 MM PITCH, 23 I/O		DOCUMENT NO: 98ASA00495D	REV: A
		STANDARD: NON-JEDEC	
		SOT1631-5	11 JAN 2016